



Material Content Data Sheet



Sales Product Name		ICE2QR1765		Issued		19. July 2018		
MA#		MA001043210						
Package		PG-DIP-8-15		Weight*		550.98 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.659	0.66	0.66	6640	6640
leadframe	inorganic material	phosphorus	7723-14-0	0.053	0.01		97	
	non noble metal	zinc	7440-66-6	0.213	0.04		387	
	non noble metal	iron	7439-89-6	4.266	0.77		7743	
wire	non noble metal	copper	7440-50-8	173.237	31.44	32.26	314415	322642
	noble metal	gold	7440-57-5	0.394	0.07	0.07	716	716
	encapsulation	organic material	carbon black	1333-86-4	1.795	0.33		3258
encapsulation	plastics	epoxy resin	-	48.470	8.80		87969	
	inorganic material	silicondioxide	60676-86-0	308.770	56.04	65.17	560398	651625
leadfinish	non noble metal	tin	7440-31-5	7.496	1.36	1.36	13605	13605
plating	noble metal	silver	7440-22-4	0.801	0.15	0.15	1453	1453
glue	plastics	epoxy resin	-	0.320	0.06		581	
	noble metal	silver	7440-22-4	1.508	0.27	0.33	2738	3319
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com